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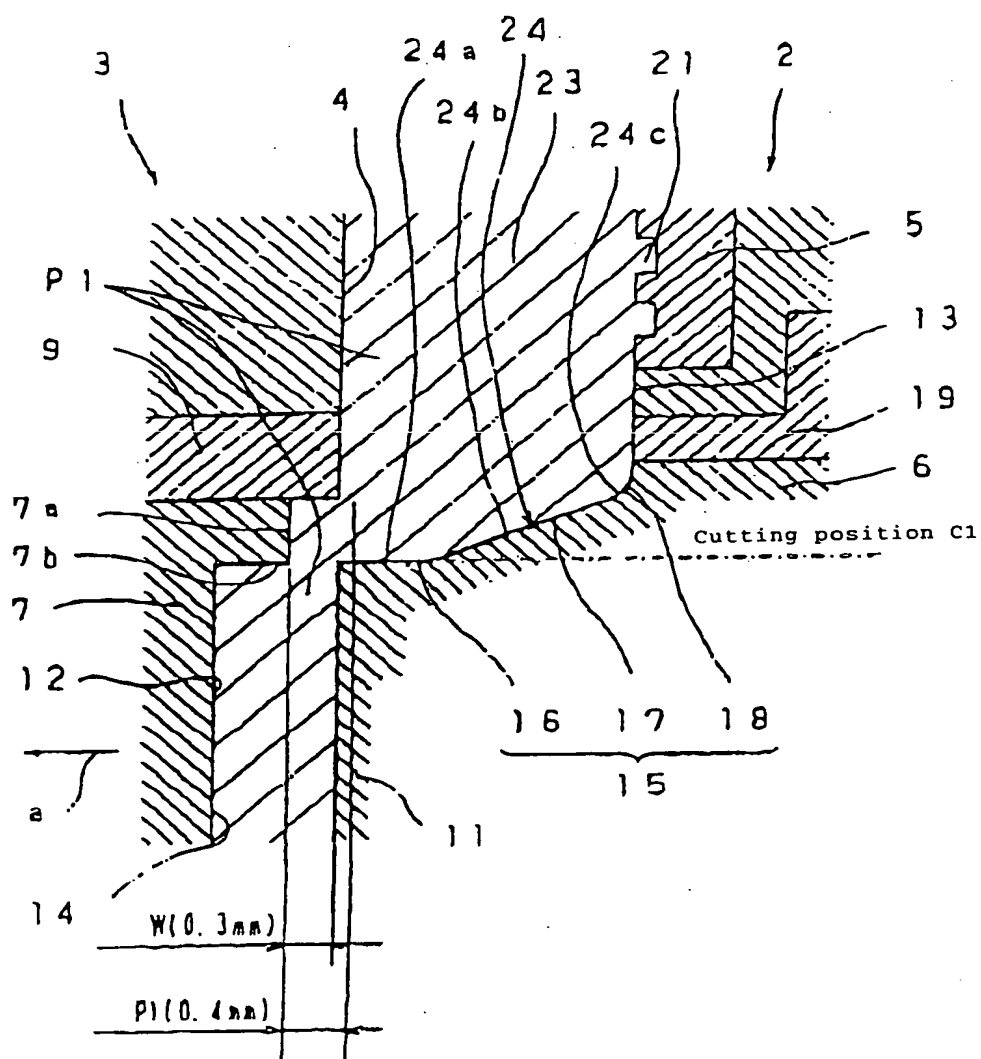


Fig.3

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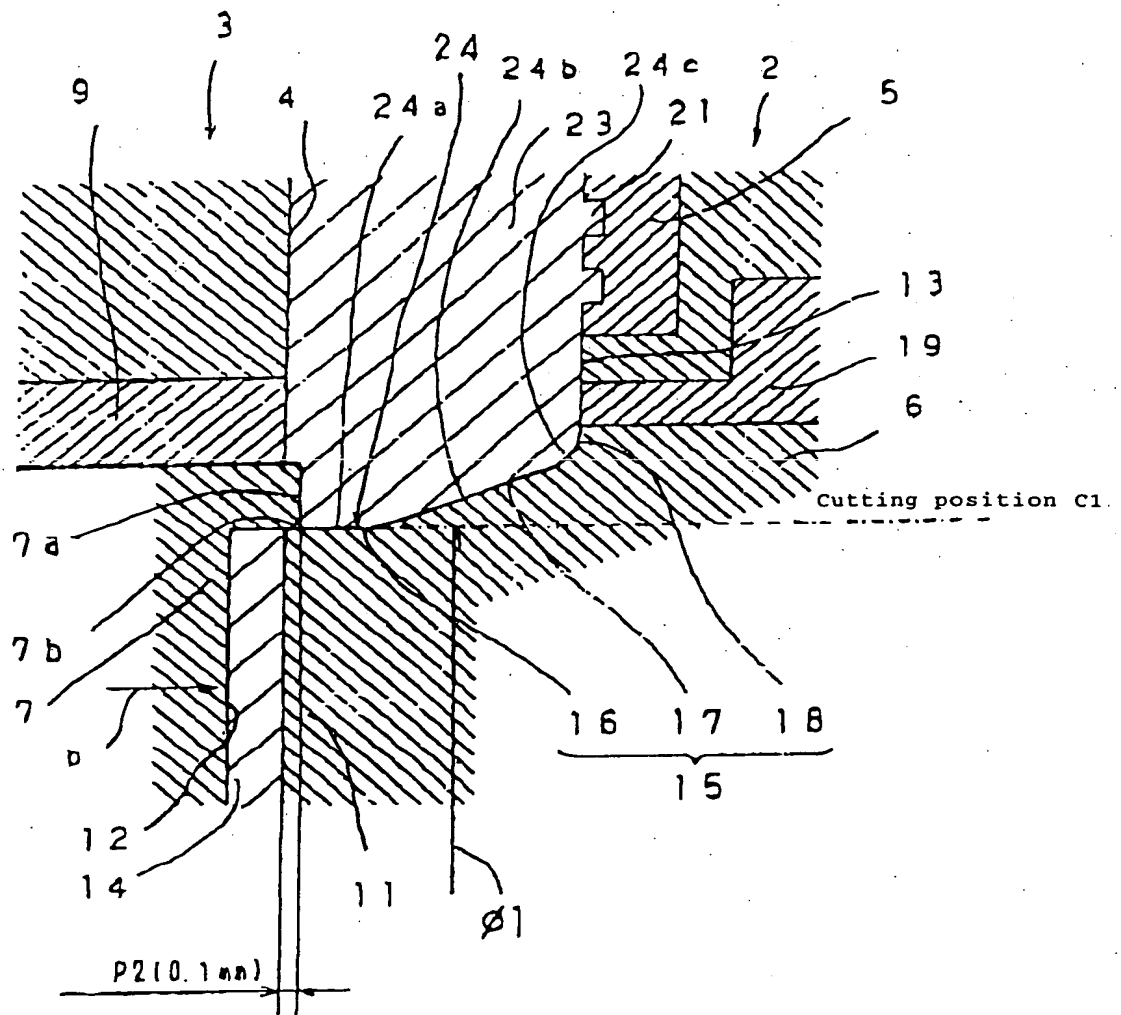


Fig.4

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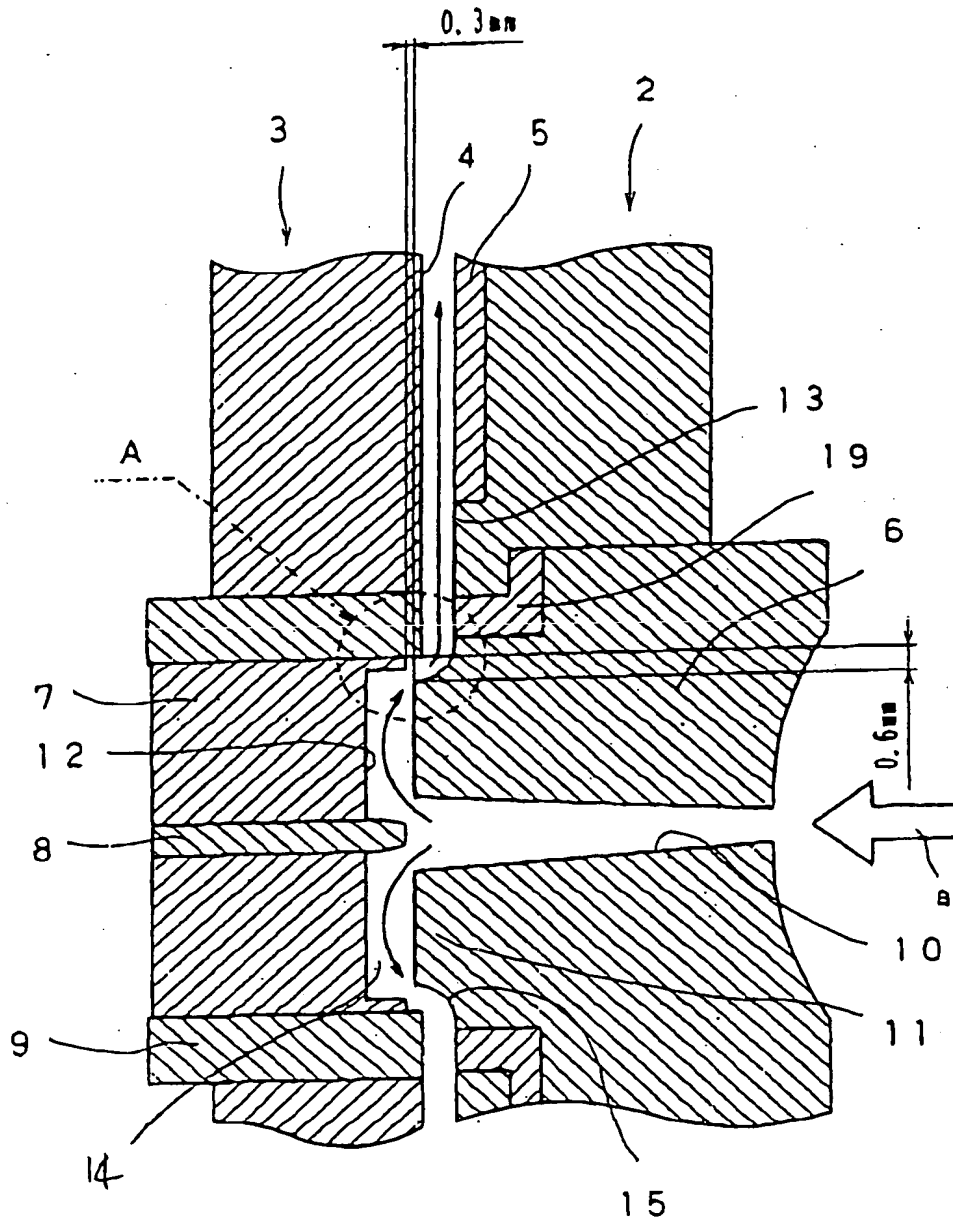


Fig.5

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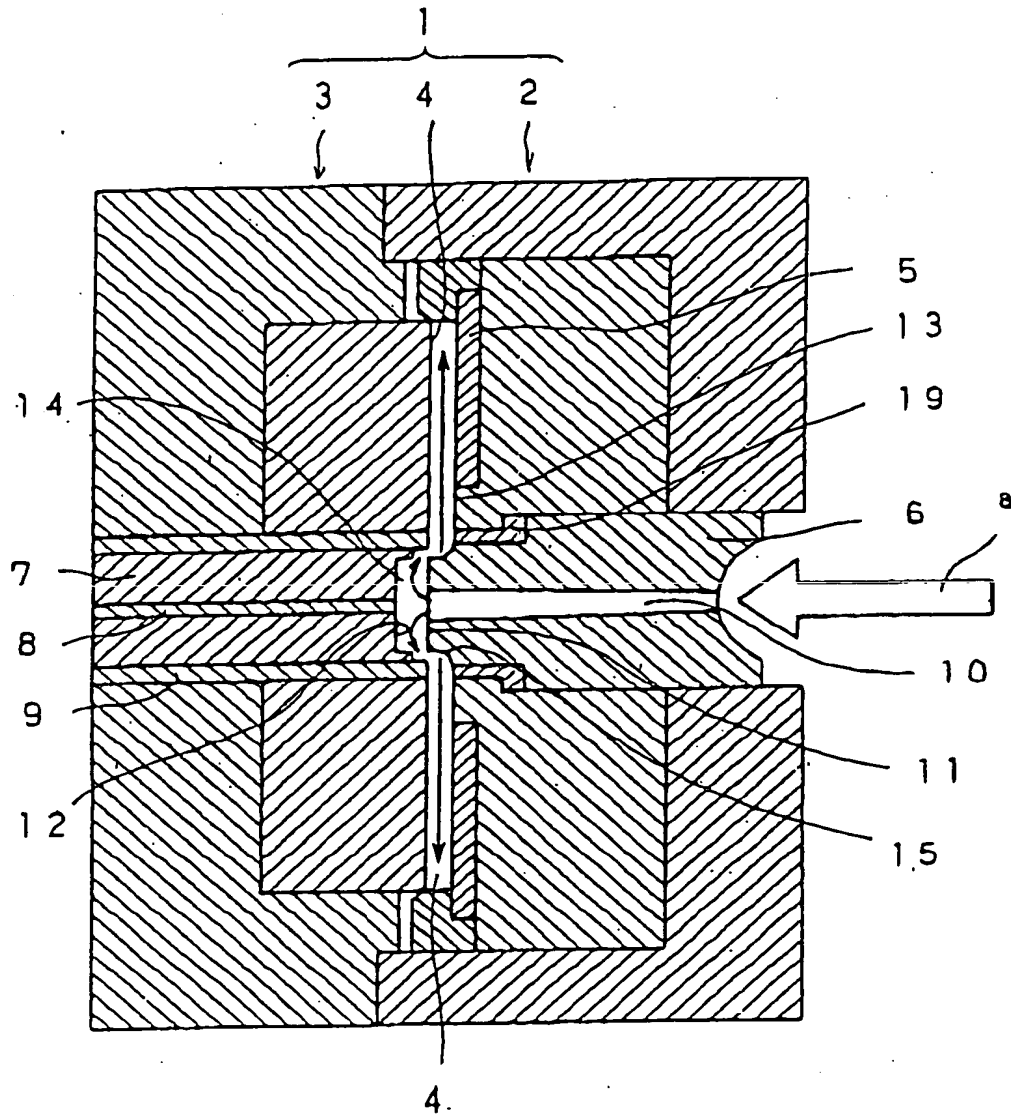


Fig.6

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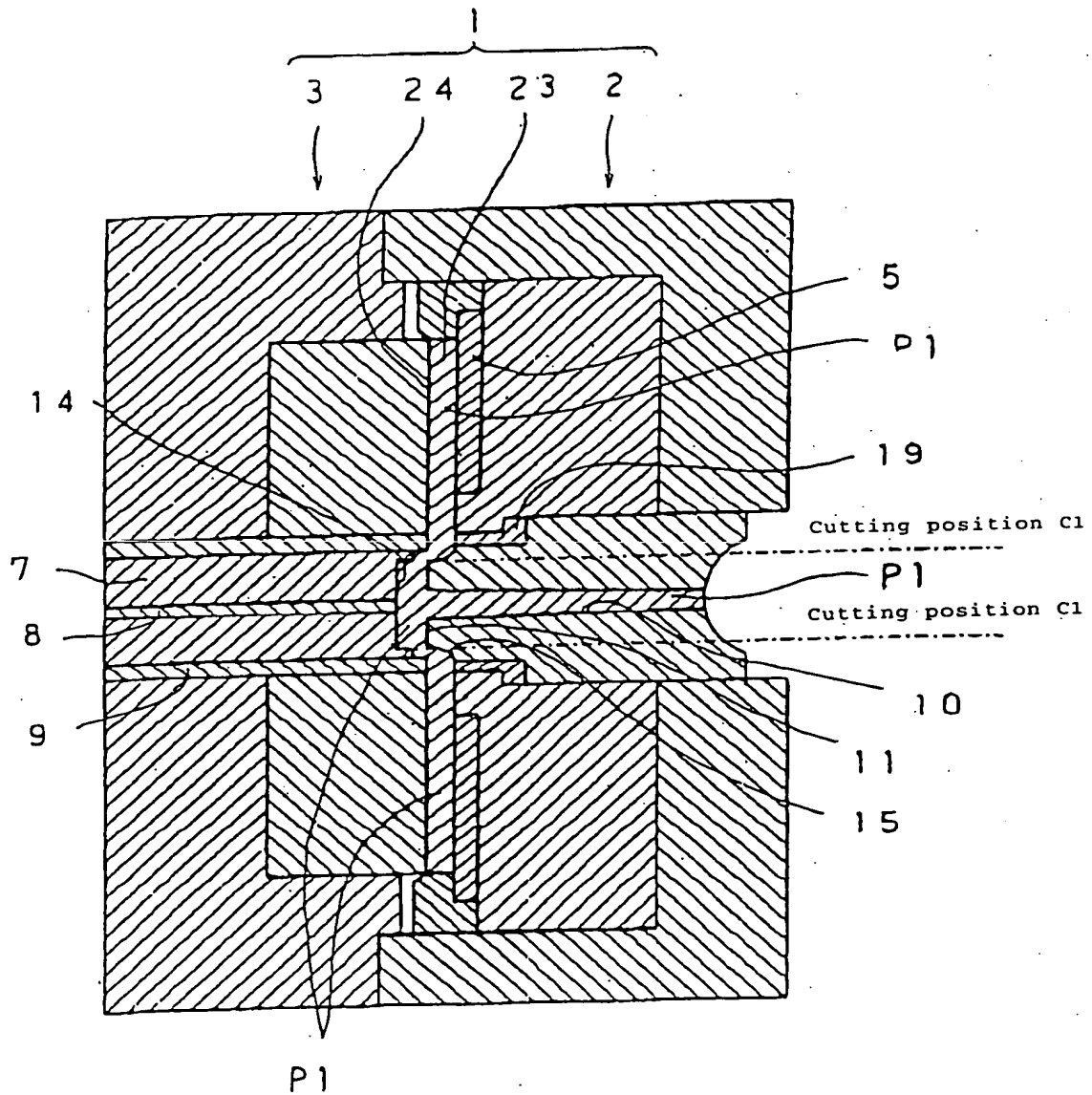


Fig.7

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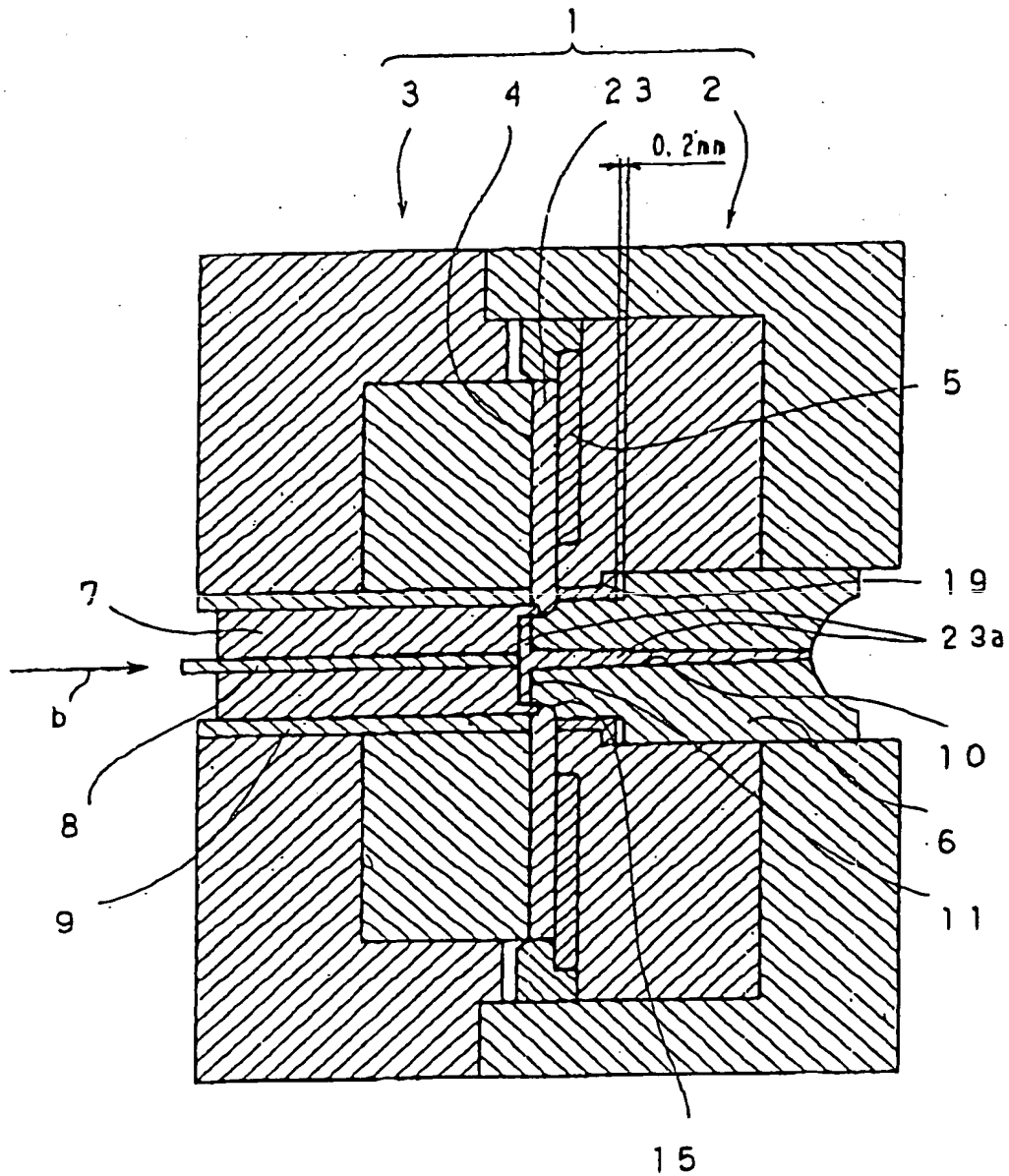


Fig.8

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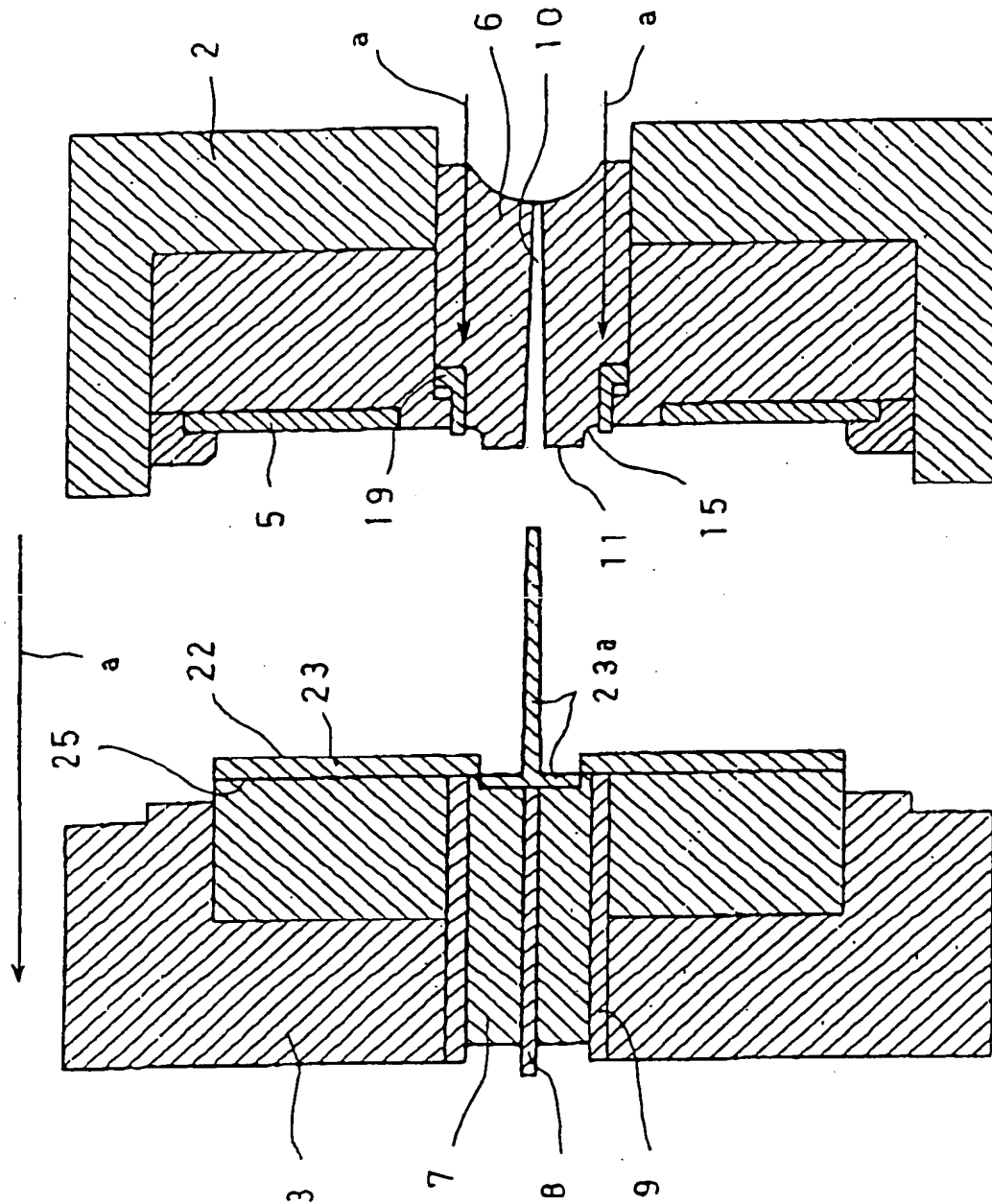


Fig.9

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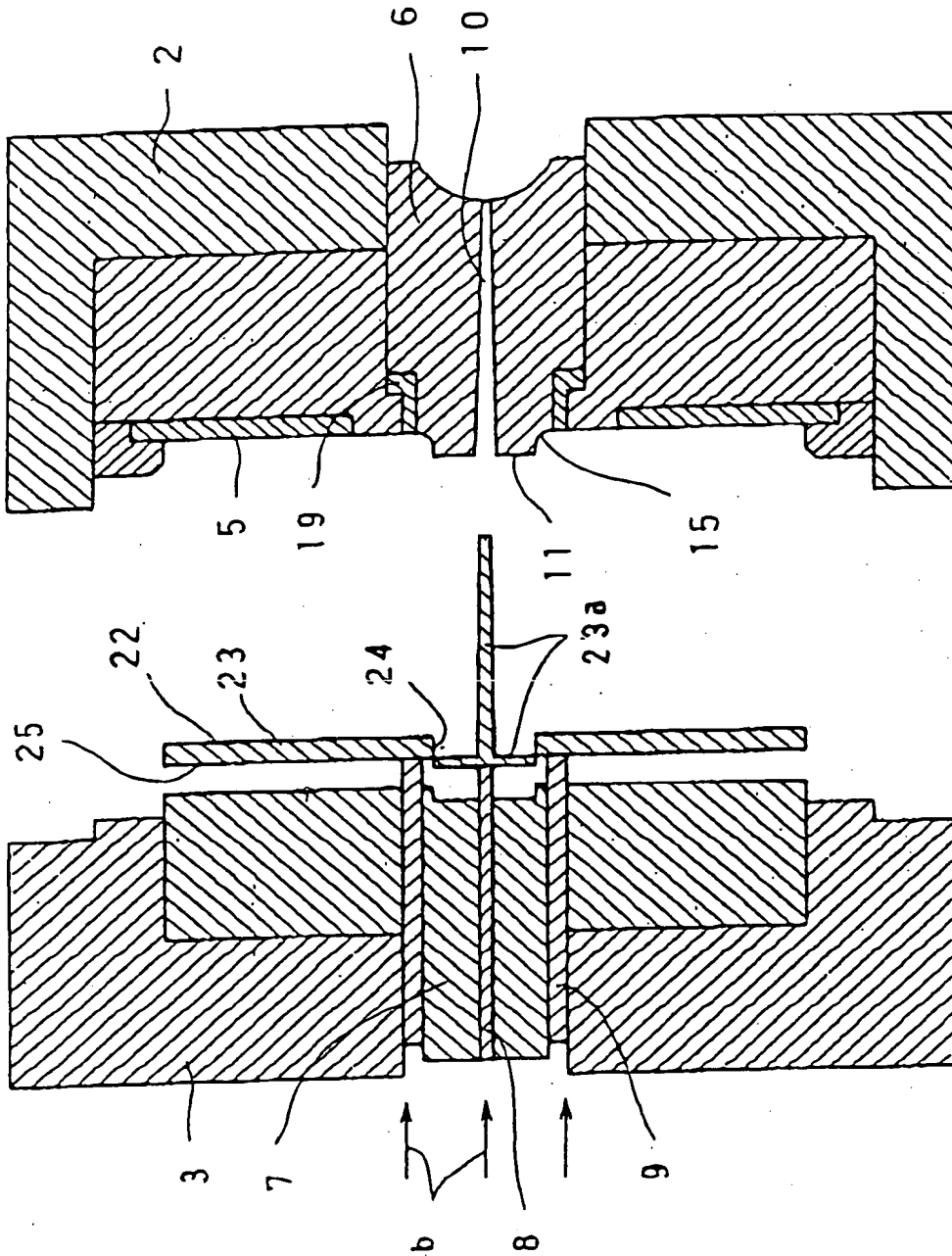


Fig.10

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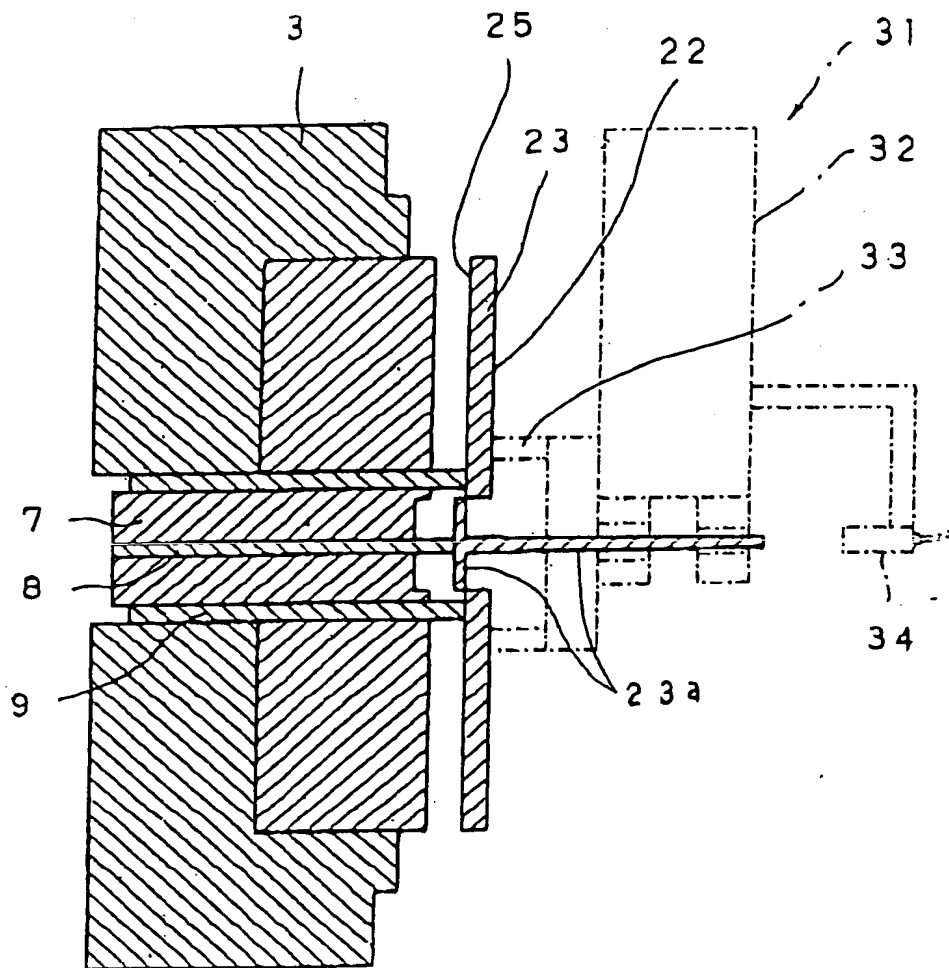


Fig.11

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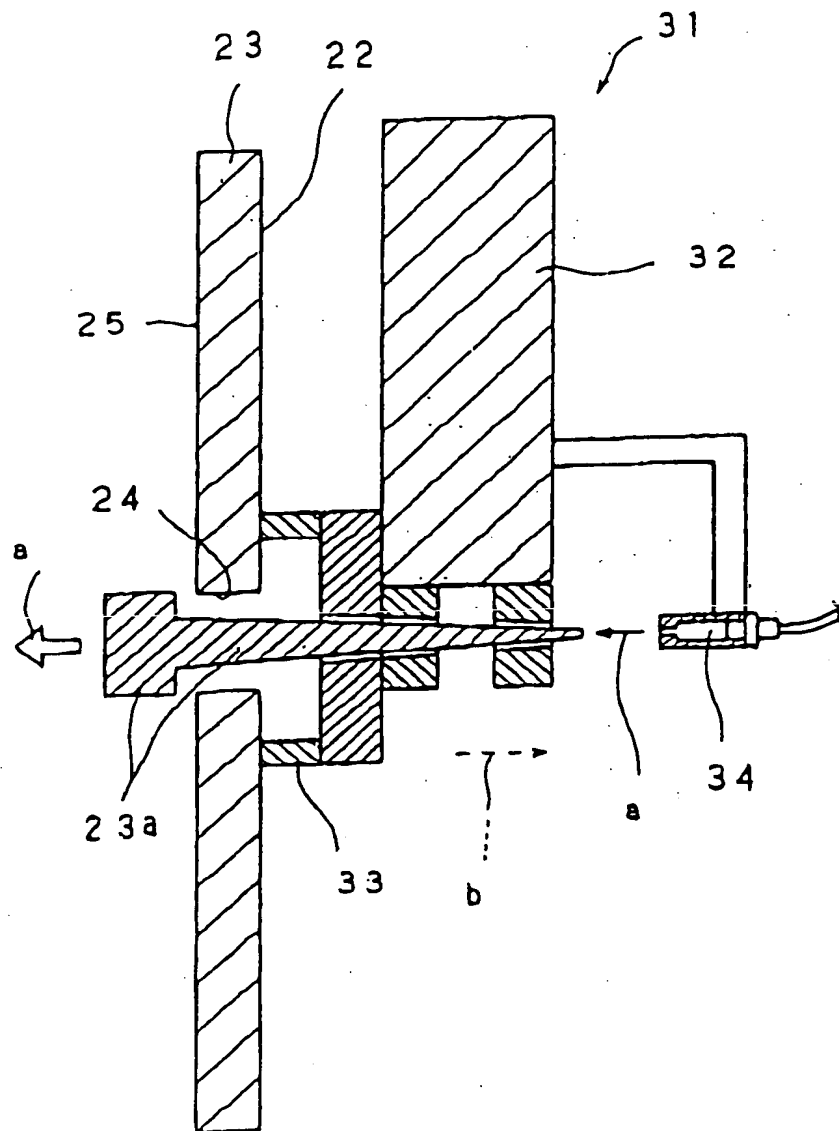


Fig.12

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| | Example 1 | Comparative Example 1 | Comparative Example 2 | Comparative Example 3 |
|--|--|-----------------------------------|---------------------------------|--|
| | Substrate of the present invention | Movable-side stamper substrate | Fixed-side stamper substrate | Comparative Example 2 removed by reamer |
| Ten measurements of eccentricity amount | 20~30 μ m | 20~30 μ m | 15~70 μ m | 20~30 μ m |

Fig.13

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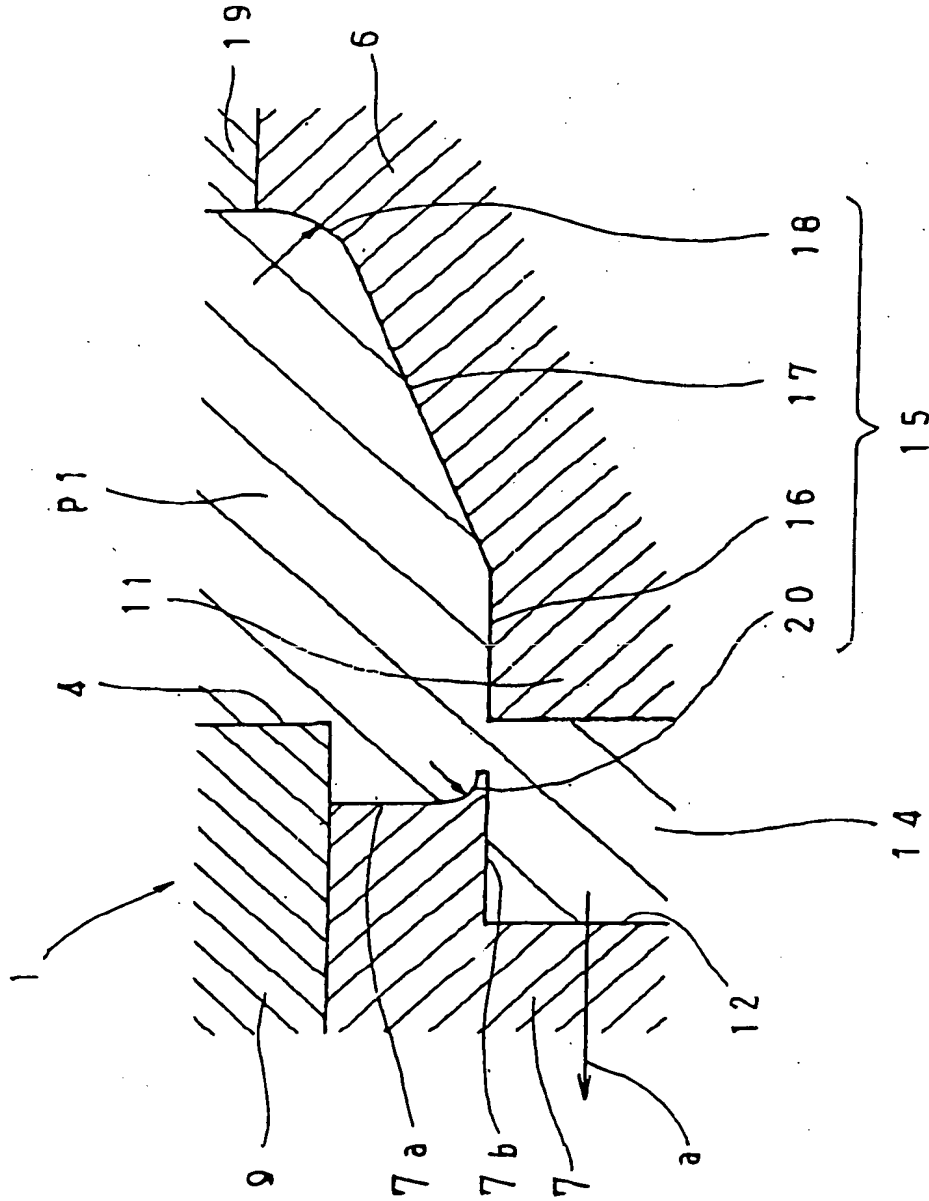


Fig.14

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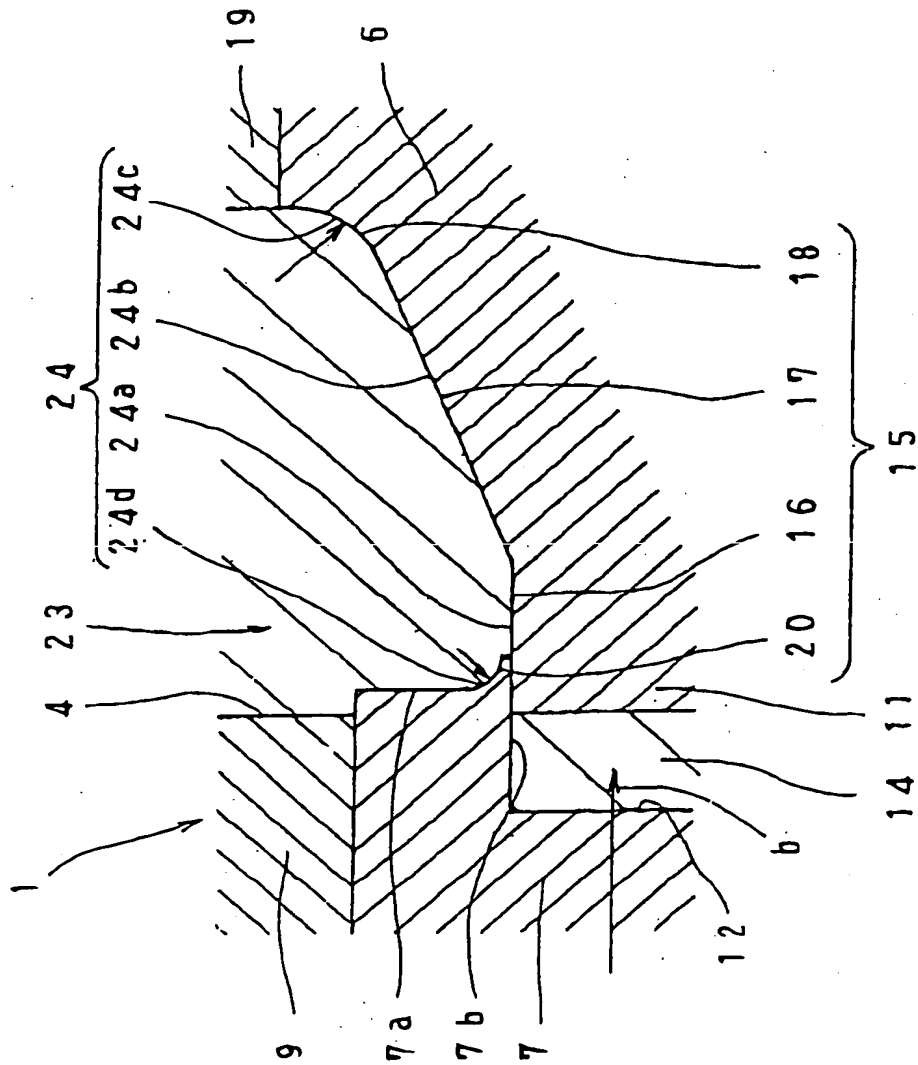
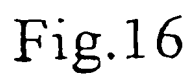


Fig.15



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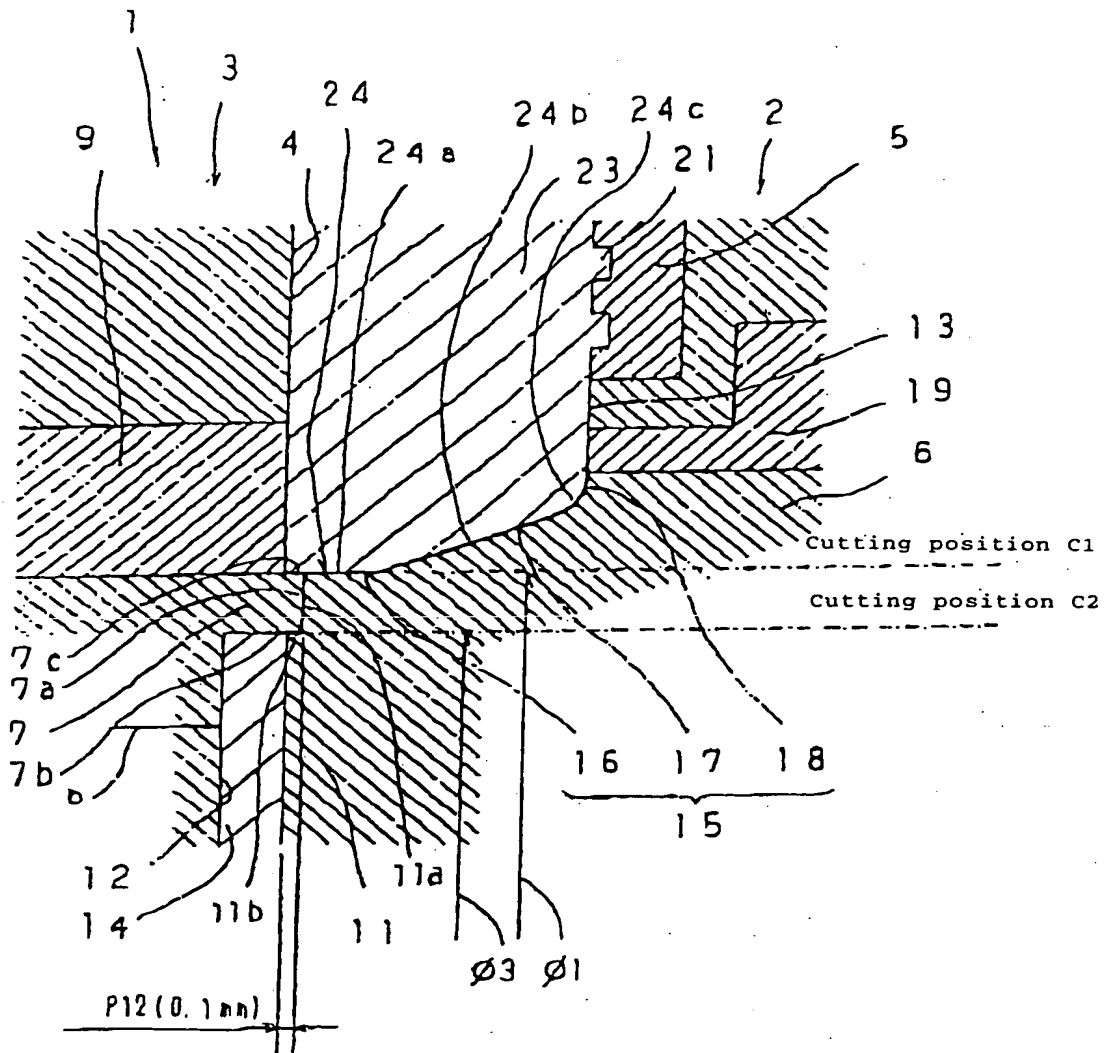


Fig.17

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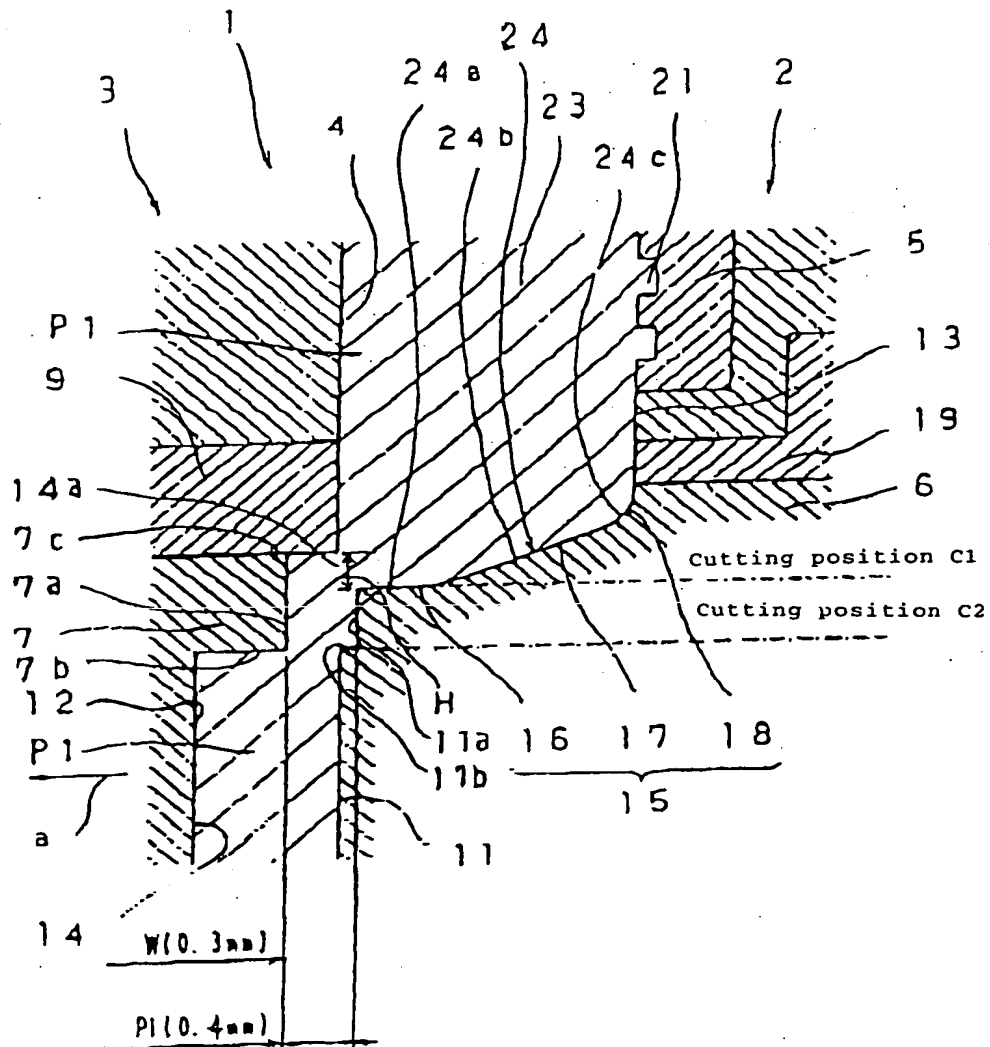


Fig.18

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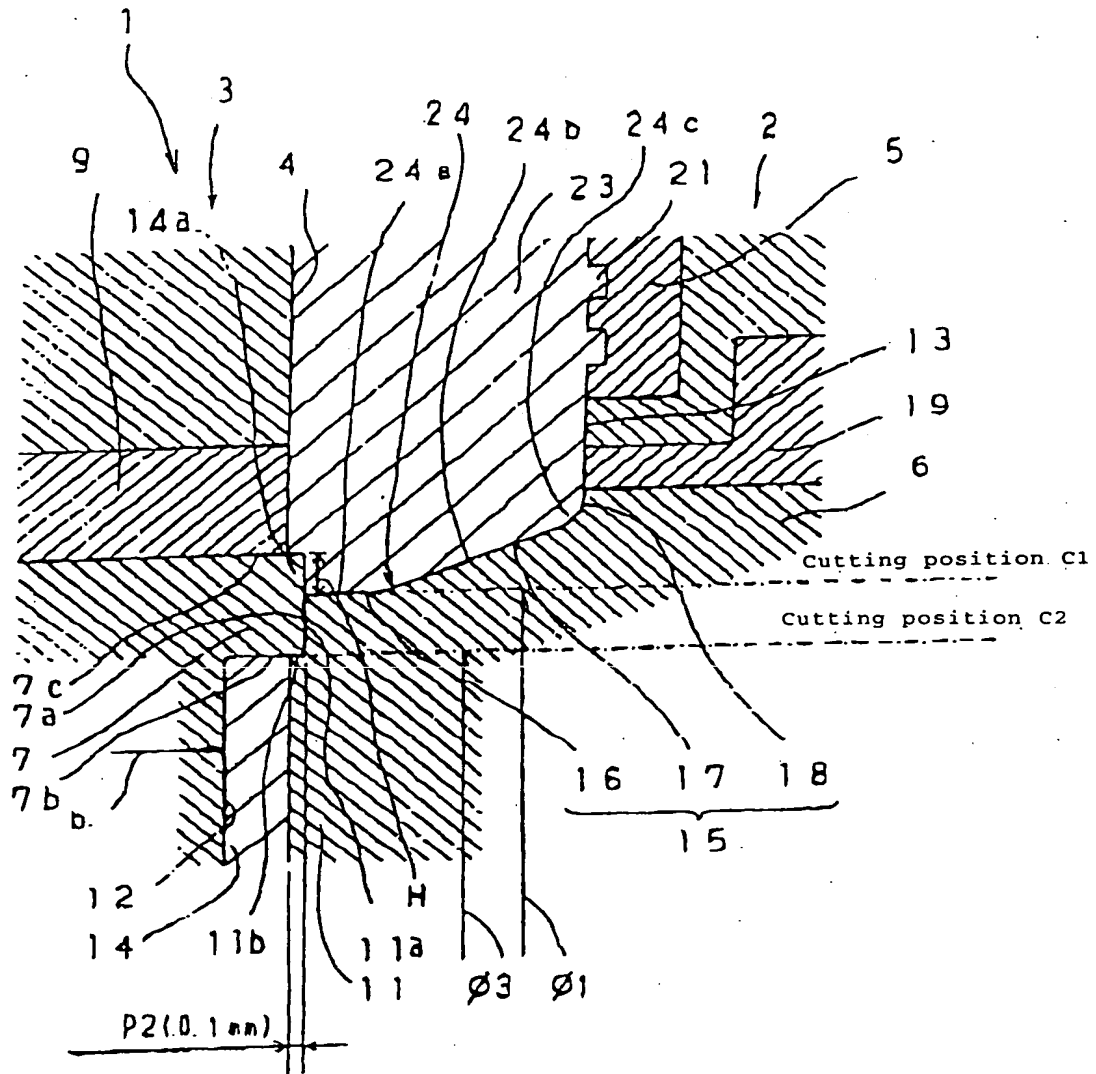


Fig.19

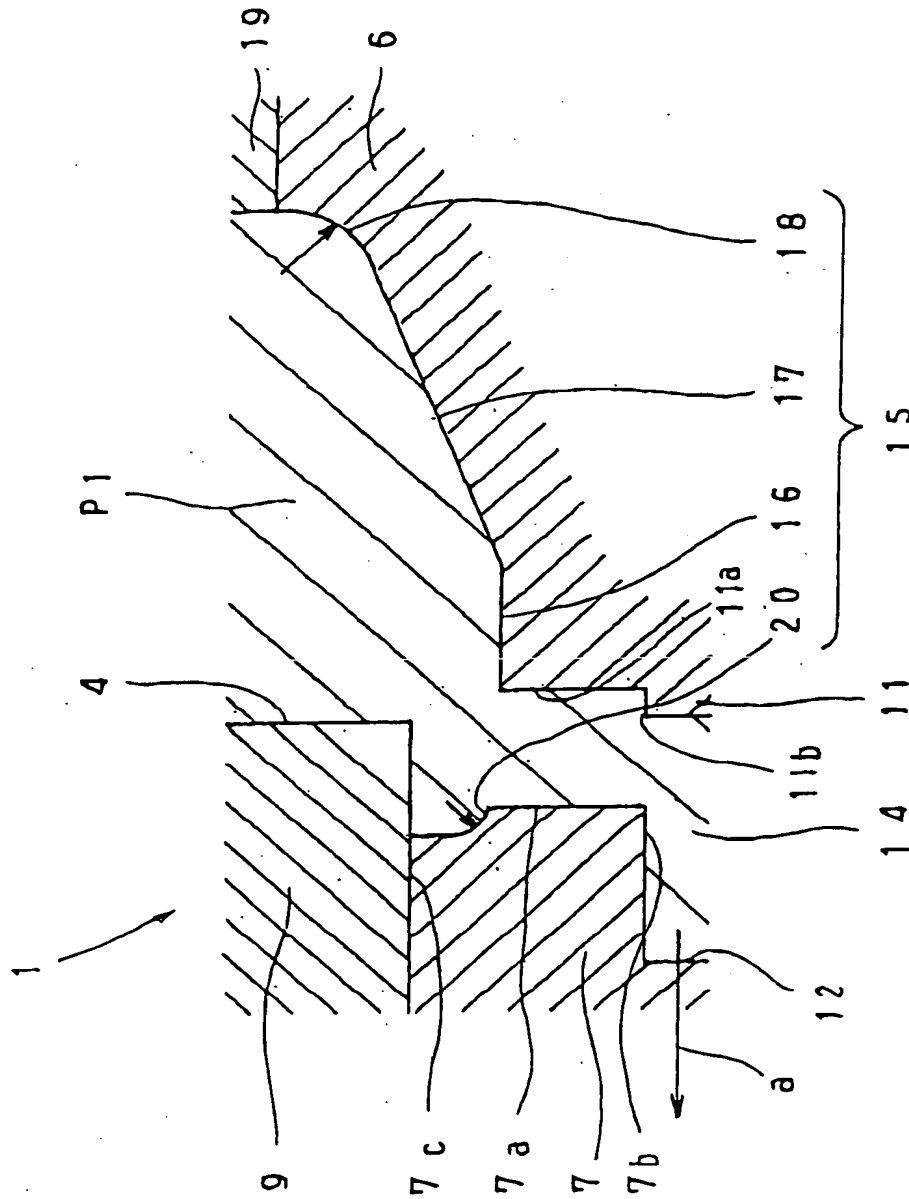


Fig.20

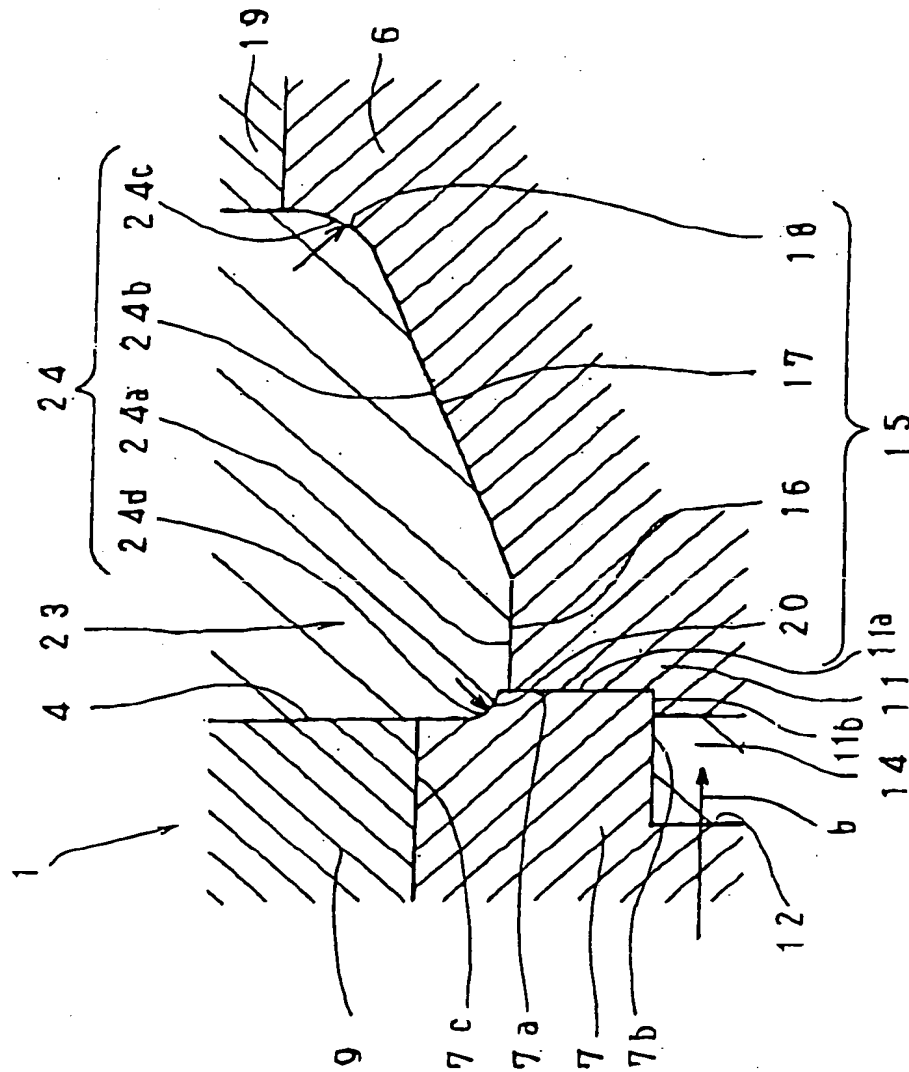


Fig.21

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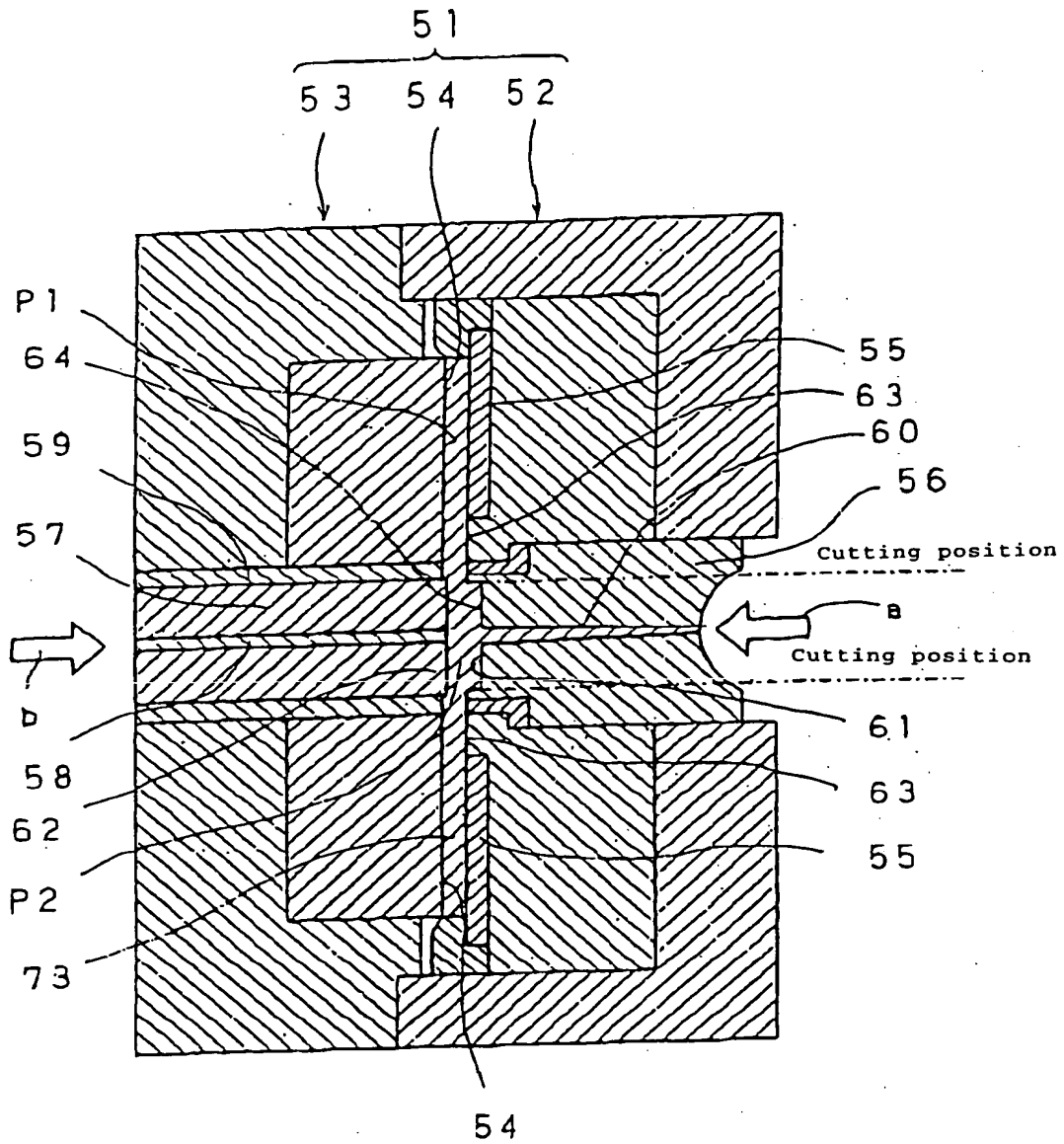


Fig.22

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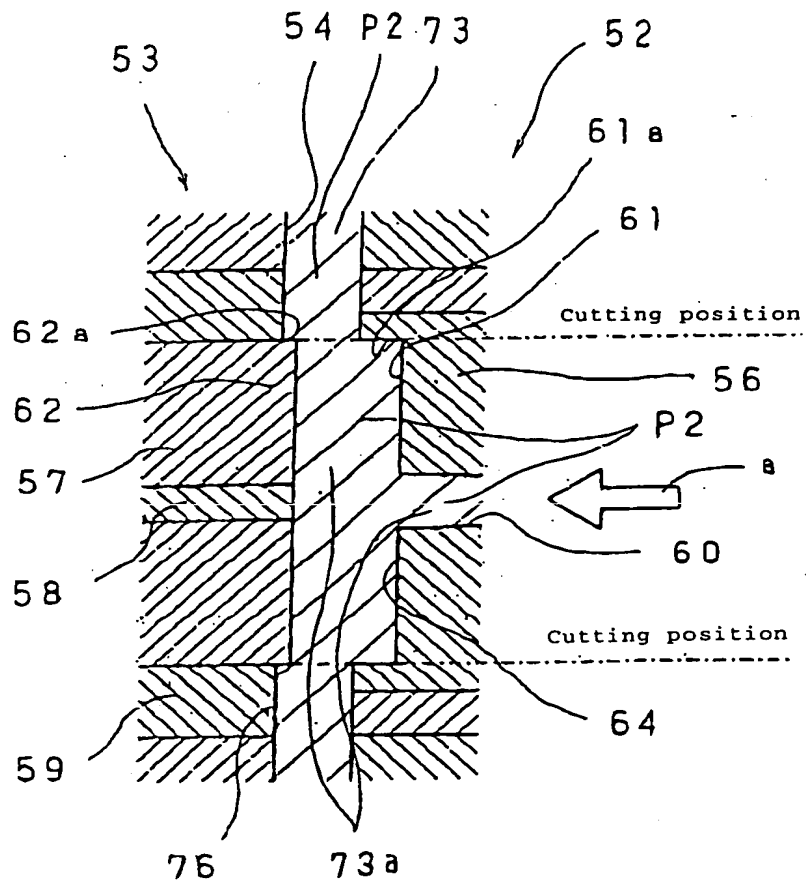


Fig.23

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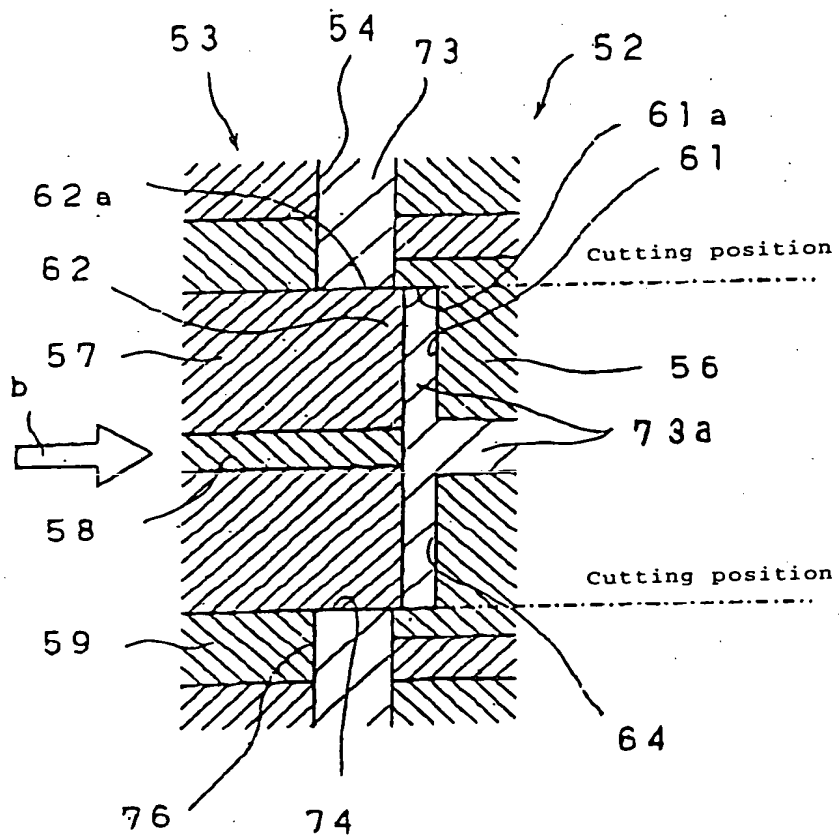


Fig.24

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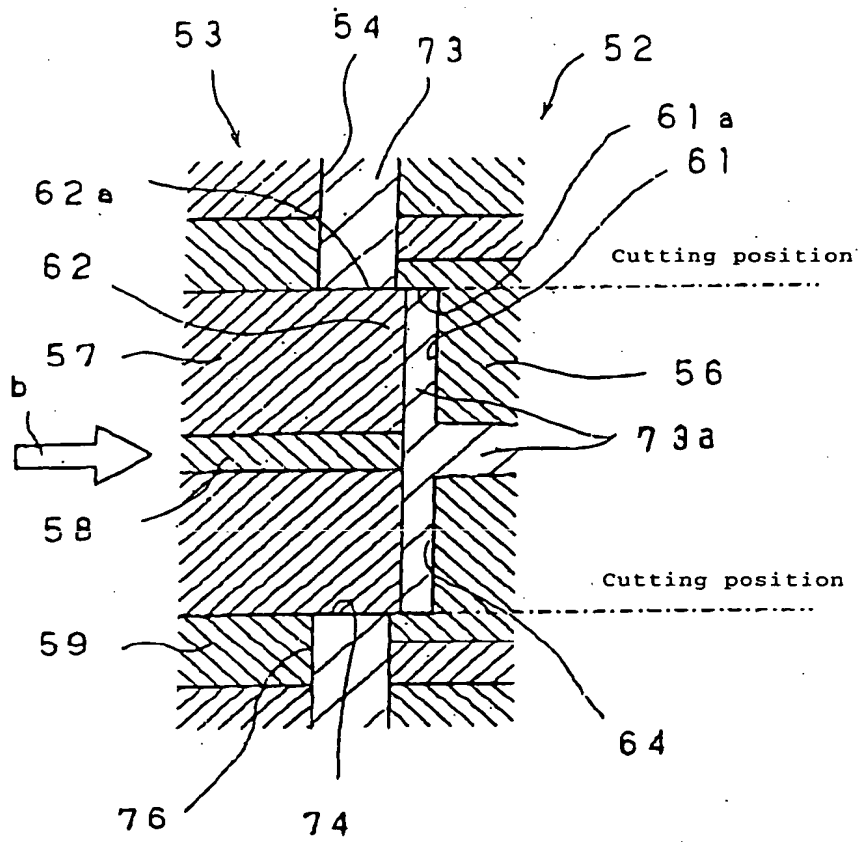


Fig.25

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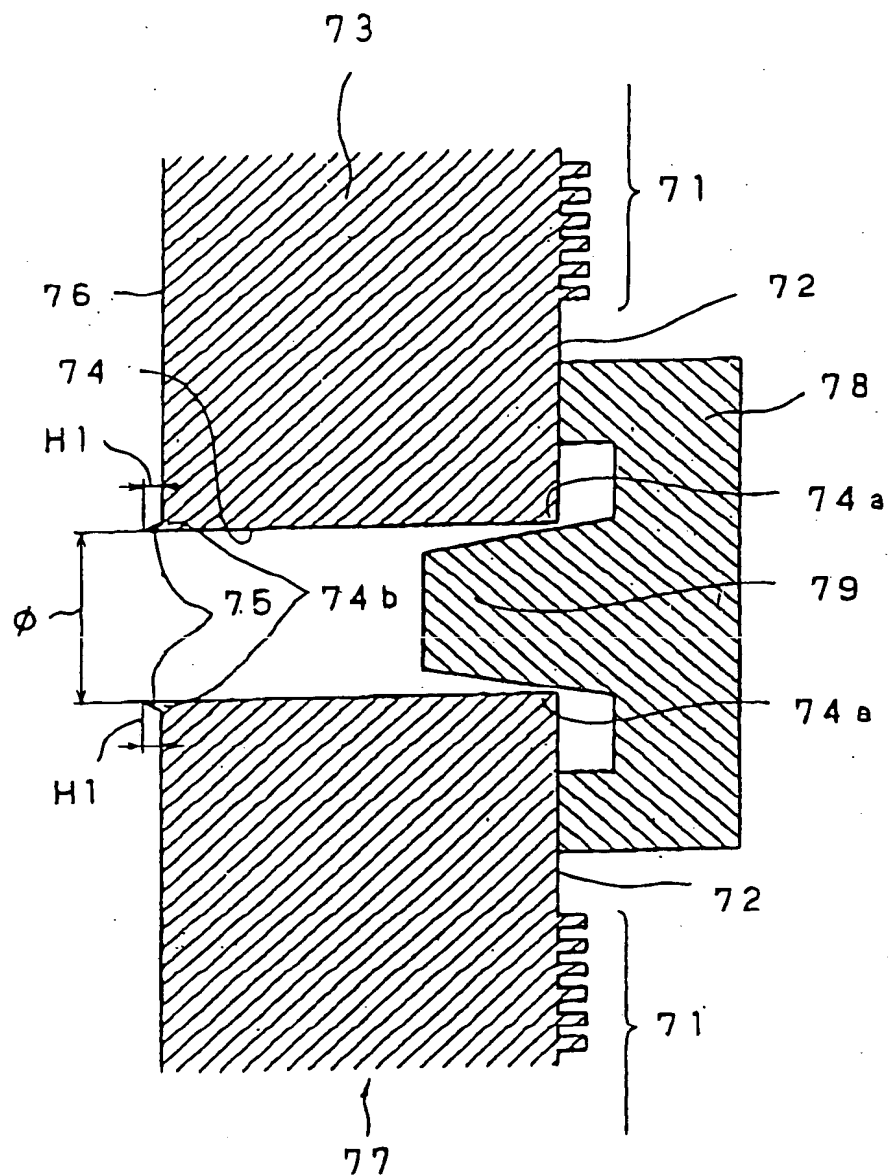


Fig.26

